High Coupling Efficiency Etched Facet Tapers in Silicon Waveguides

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Abstract—We demonstrate a platform based on etched facet silicon inverse tapers for waveguide-lensed fiber coupling with a loss as low as 0.7 dB/facet. This platform can be fabricated on a wafer scale enabling mass-production of silicon photonic devices with broadband, high-efficiency couplers.

Index Terms—Waveguides, coupler, inverse tapers, photonics.

The two main approaches for coupling light on a high-confinement chip with submicron waveguides are gratings, which suffer from inherently low bandwidth, or taper couplers, which require one-die-at-a-time processing to achieve high coupling efficiency for end-fire coupling [1]–[28]. Grating couplers are inherently bandwidth-limited and require complex fabrication for high efficiency coupling. Most gratings show coupling loss (to/from a cleaved single mode fiber) of a few dB (∼2–6 dB) with a 3 dB bandwidth of tens of nanometers [5], [9], [11], [13], [17], [21] while complex, multi-etch gratings with bottom reflectors have reached sub-dB loss with broader bandwidth [24], [25], [27], [28]. A few other proposed approaches for grating geometries are based on transformation optics [29], [30], parabolic reflectors [31], and subwavelength grating tapers [32], [33], however they also suffer from the bandwidth-efficiency tradeoff. Most inverted couplers show lower coupling loss than gratings, typically less than 1 dB, with 3 dB bandwidth of hundreds of nanometers [1], [4], [14], [20], [24]. More complex inverse tapers using multiple coupling stages and suspended structures can reach sub-dB coupling loss for lensed fiber input and 1–2 dB for standard cleaved fibers [19], [22], [23], [26]. However, to date, taper coupler structures require one-die-at-a-time mechanical polishing to achieve smooth surfaces for high coupling efficiency. Some works have reported coupling using facet etching [7], [20], [23], [34]; but they consist of (a) multi-stage or suspended taper structures that require more complex fabrication and might be susceptible to vibrations or (b) tapers terminated directly at the etched facet [7], [34], which require a challenging etch process to avoid distortion of the taper tip and other fine features on a chip and therefore might limit its implementation in wafer scale production.

Here we show a platform for tapered waveguide coupling structures based on etched facet using a single simple etching process with high efficiency fiber-waveguide coupling suitable for fabrication on a wafer scale. The challenge in traditional etching of the waveguide facets is that the reactive ion etching process must etch through multiple materials at the same time, e.g., oxide from the cladding and silicon from the nanotaper. The different etch rate for the oxide and silicon creates artifacts that distort the silicon taper facet and lead to coupling loss. Here we overcome this challenge by terminating the silicon nanotaper with an oxide gap and etching the facet at the wafer-level to obtain a high-quality coupling interface. Instead of defining the facets of the waveguide at the end point of the taper, we leave a gap between the end of the taper and the coupling facet (Fig. 1). The gap is composed of the overcladding material, which in this case is silicon dioxide. Leaving the oxide gap ensures etching of only one material throughout the cross-section of the facet, which enables fabrication of a smooth and vertical surface for high efficiency coupling.

We show that since the optical mode is focused at the tip of the nanotaper, the effect of the oxide gap on the coupling efficiency is small. We simulate the tapered waveguides with the oxide gap etched facet using a 3D Finite Difference Time Domain (FDTD) approach and show that the oxide gap has a weak effect on the mode matching between the lensed fiber and the nanotaper. The Si waveguide is linearly tapered down from its 500 nm width to a 160 nm tip over a length of 100 µm. First we determine the launch position of the lensed optical fiber mode (working distance of 14 µm, spot size of 2.5+−0.5 µm) using Gaussian optics to account for the presence of the oxide gap. Then we launch the lensed optical fiber mode at the oxide-air interface such that it focuses at the correct spot size at the silicon taper tip. Propagation in the oxide gap and silicon taper is simulated with 3D FDTD. The launched fiber mode has a spherical wavefront. To calculate the coupling efficiency, we simulate the mode propagation through the taper and monitor the total...
power in the waveguide. As shown in Table I, the results of our simulations reveal that, for a top SiO₂ cladding that is 2 μm or greater, and an oxide gap that is 2 μm or larger, the additional coupling losses due to the presence of the oxide gap are less than 0.3 dB, indicating that the oxide gap has a weak effect on the mode matching between the lensed fiber and the nanotaper. We attribute losses in our simulations to two factors: the discretization of the 3D simulation domain (computer memory versus simulation accuracy trade-off, these losses should be constant for all simulations as the discretization does not change), and the fact that for longer oxide gaps, the optical field coming from air and hitting the air-oxide interface has a larger diameter (to ensure that the 2.5 micron spot size is at the Si taper tip), and this results in more optical field interacting with the Si substrate leading to loss. This last source of loss is especially more important when the top oxide cladding is thin (~1 micron).

To characterize the coupling loss of the etched facet nanotapers with oxide gap, we fabricate 250 nm by 500 nm waveguides of 0.69 mm, 2.78 mm, and 4.37 mm in length, with oxide gaps ranging from 2 to 6 μm. The waveguides are patterned with e-beam lithography, etched in a chlorine chemistry and clad with 2.4 μm of PECVD silicon oxide. Then, openings are patterned using contact photolithography to define the inverse taper waveguide facets and the silicon dioxide (both the PECVD overcladding and the buried oxide) is etched in an ICP RIE using a CHF₃/O₂ chemistry. Finally the silicon substrate is deep etched using the Bosch process so that the chip facet can be accessed with a lensed fiber (see SEM of taper on Fig. 2).

We measure a coupling loss as low as 0.7 dB per facet for a nanotaper tip width of 160 nm and oxide gap of 2 μm at a wavelength of 1550 nm. Note that the inverse taper insures that only the fundamental mode is coupled into the waveguide. The coupling loss is measured using the “cut-back” method. We measure the throughput of the waveguides of different lengths and fit the results to a straight line (Fig. 3a). The point where the fitted line crosses the y-axis indicates the insertion loss of the two nanotapers. We then measure the throughput of the lensed fibers (working distance of 14 μm, spot size of 2.5±0.5 μm) back-to-back (with no silicon die present) and determine that their loss is 1.6 dB. To calculate the coupling loss, we subtract the lensed fiber losses from the insertion loss measured via the “cut-back” method. This method to measure coupling loss accounts for the propagation loss in the taper itself as well as the mode matching loss to the input fiber and excludes the losses due to the fiber/lensed-fiber transition. For a 2-μm oxide gap we measured an insertion loss of 3.1 dB with a low coupling loss of 0.7 dB per facet. All devices with oxide gaps between 2 and 6 μm had a coupling efficiency within a range of 0.5 dB (Fig. 3b).

The measured low coupling loss per facet of 0.7 dB can in principle be lowered down to the theoretical value of 0.2 dB by improving the quality of the photolithography and the PECVD oxide. We show the expected coupling loss per facet in Fig. 3b (dashed line). One can see that the simulations predict even lower coupling losses. The discrepancy between the simulated values and the measured ones is mostly due to fabrication imperfections. These imperfections can be seen in Fig. 2 where the roughness is clearly visible.
Fig. 3. (a) Output power vs. different waveguide lengths for an oxide gap of 2 µm. The insertion loss of the waveguide corresponds to the zero crossing of the straight line (solid line in graph) fitted to the data. (b) Coupling loss per facet vs. oxide gap. Solid symbols show measured data. The line is a guide to the eye. Dashed line shows simulated coupling loss versus oxide gap. The coupling loss per facet is calculated by subtracting.

REFERENCES


